

AMENDMENTS TO THE CLAIMS:

This listing of claims replaces all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (Currently Amended) A method comprising:

forming a first electrode and a second electrode made from a first material on a base body
made from a second material; and
immersing the base body, the first electrode, and the second electrode in an etching
solution directly after having formed the first and the second electrode on the base body, wherein
upon immersion chemically etching at least a portion of the base body ~~with an~~ is chemically
etched etching solution to adjust ~~and wherein~~ a resistance of the base body between the first
electrode and the second electrode is adjusted;

~~wherein the first and second electrodes are made from a material [[that]] is etched~~
~~etchable, by the etching solution, and wherein the first material is etched substantially less than~~
~~the base body is etchable by the etching solution second material.~~

2. (Original) The method of claim 1, wherein the base body comprises a ceramic
material.

3. (Original) The method of claim 1, wherein the base body comprises a material having
a resistance with a negative temperature coefficient.

4. (Original) The method of claim 1, wherein a length of an edge of the base body is less than about 3 mm.

5. (Canceled)

6. (Previously Presented) The method of claim 1, wherein the etching solution is sulfuric acid.

7. (Original) The method of claim 1, further comprising measuring a value of a resistance of the base body prior to chemically etching the at least a portion of the base body.

8. (Canceled)

9. (Original) The method of claim 1, further comprising:
determining a difference between the predetermined value and a measured value of the resistance; and

determining a duration for the chemically etching based on said difference, wherein chemically etching at least a portion of the base body comprises chemically etching at least a portion of the base body for the duration.

10. (Original) The method of claim 1, wherein forming the first electrode and the second electrode on the base body comprises forming the first electrode at a location opposite the second electrode on the base body.

11. (Original) The method of claim 1, wherein chemically etching at least a portion of the base body to adjust the resistance of the base body comprises chemically etching at least a portion of the base body to adjust the resistance of the base body to a predetermined value.

12. (Previously Presented) The method of claim 1, wherein the first and second electrodes comprise a multilayer metallization comprising a Ag/Ni/Sn layer sequence.

13. (Previously Presented) The method of claim 1, wherein the first and second electrodes comprise a silver/palladium metallization.

14. (Currently Amended) A method comprising:
forming a first electrode and a second electrode on a base body; and
immersing the base body, the first electrode, and the second electrode in an etching solution directly after having formed the first and the second electrode on the base body, wherein upon immersion chemically etching at least a portion of the base body with an is chemically etched etching solution to adjust and wherein a resistance of the base body between the first electrode and the second electrode is adjusted,

wherein the first and second electrodes comprise a multilayer metallization comprising a Ag/Ni/Sn layer sequence, and

wherein the first and second electrodes are etched etchable, by the etching solution, and
wherein the first and second electrodes are ethced substantially less than the base body is etched
~~etachable by the etching solution.~~

15. (Currently Amended) A method comprising:

forming a first electrode and a second electrode on a base body; and
immersing the base body, the first electrode, and the second electrode in an etching
solution directly after having formed the first and the second electrode on the base body, wherein
upon immersion chemically etching at least a portion of the base body ~~with an~~ is chemically
etched etching solution to adjust and wherein a resistance of the base body between the first
electrode and the second electrode is adjusted;[[,]]

wherein the first and second electrodes comprise a silver/palladium metallization, and
wherein the first and second electrodes are etched etchable, by the etching solution, and
wherein the first and second electrodes are ethced substantially less than the base body is etched
~~etachable by the etching solution.~~